

<b>Adhesion Promoters</b> <ul style="list-style-type: none"> <li><b>PC-1531:</b> Acid cleaner to improve dry film photoresist adhesion. Immersion only</li> <li><b>PC-1532:</b> Sprayable acid cleaner to improve dry film photoresist adhesion.</li> </ul>
<b>Anti-Foam</b> <ul style="list-style-type: none"> <li><b>AF-5:</b> Blocked Copolymer, nonionic surfactant.</li> <li><b>AF-6:</b> Solvent based surfactant.</li> <li><b>AF-7:</b> Blocked Copolymer, nonionic surfactant.</li> </ul>
<b>Anti-Tarnish</b> <ul style="list-style-type: none"> <li><b>AT-23:</b> Citric acid and triazole based solution.</li> <li><b>AT-25:</b> Triazole based solution.</li> <li><b>AT-26:</b> Copper cleaner/anti-tarnish additive for pumice scrubbing operations.</li> </ul>
<b>Copper Cleaners</b> <ul style="list-style-type: none"> <li><b>ALC-1:</b> Alkaline cleaner, immersion or spray.</li> <li><b>ILC-2:</b> Acid cleaner for spray applications.</li> <li><b>ILC-3:</b> Tri-acid cleaner for spray applications.</li> <li><b>ILC-V:</b> Acid cleaner for VLP coppers/wet lam.</li> <li><b>OLC-100:</b> Pattern plate cleaner.</li> </ul>
<b>Copper Thinning / Half Etch</b> <ul style="list-style-type: none"> <li><b>CR-2180:</b> Hydrogen peroxide/sulfuric acid copper etching process designed to evenly reduce copper foil thickness prior to the fine etching operations.</li> </ul>
<b>Cupric Chloride Etch</b> <ul style="list-style-type: none"> <li><b>CuRep 28:</b> Reduced sodium chlorate, high sodium chloride for use with Vis-U-Etch control systems.</li> <li><b>CuRep 40:</b> Sodium chlorate based regenerative formula with etch rate enhancers and banking agents.</li> </ul>
<b>Dry Film / LPI Developers</b> <ul style="list-style-type: none"> <li><b>DV-6200:</b> Developer with 200 g/l sodium carbonate.</li> <li><b>DV-6400:</b> Developer with 400 g/L sodium and potassium carbonate.</li> <li><b>DV-6450:</b> Developer with 450 g/L sodium and potassium carbonate.</li> <li><b>DV-6600:</b> Developer with 600 g/L potassium carbonate and cleaner.</li> <li><b>DV-6601:</b> Developer with 600 g/L potassium carbonate without cleaner.</li> </ul>

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<b>Dry Film Strippers - Innerlayers</b> <ul style="list-style-type: none"> <li><b>FS-60:</b> Low cost amine/caustic blend.</li> <li><b>FS-63:</b> Amine blend.</li> <li><b>FS-68:</b> Low VOC (88 g/l) caustic/amine blend.</li> </ul>
<b>Dry Film Strippers – Outerlayers</b> <ul style="list-style-type: none"> <li><b>FS-72:</b> Amine blend for stripping fine line outerlayers with overplated circuits.</li> <li><b>FS-74:</b> Amine blend for hard to strip dry films.</li> <li><b>FS-79:</b> Semi-aqueous stripper with alkaline amines and glycol ethers to provide smallest particles possible.</li> <li><b>FS-5561:</b> General purpose. . Inners and outers.</li> </ul>
<b>Equipment Cleaners</b> <ul style="list-style-type: none"> <li><b>SC-80:</b> Concentrated, reusable alkaline equipment cleaner for developers, etchers and strippers.</li> <li><b>SM-85:</b> Alkaline cleaner for developers, etchers and strippers. Recommended for LPI developers.</li> <li><b>SC-86:</b> Contains mild solvent to remove organic filler residues associated with certain photoresists.</li> <li><b>SC-1310:</b> Acidic cleaner designed specifically to clean residues from ferric chloride etching systems.</li> <li><b>SC-1315:</b> Organic acid based cleaner for developer and resist strip modules.</li> </ul>
<b>Immersion Tin</b> <ul style="list-style-type: none"> <li><b>I-Tin 8800:</b> Cost effective, tin plating process.</li> </ul>
<b>HAL &amp; Reflow</b> <ul style="list-style-type: none"> <li><b>VHF-202:</b> Vertical HAL flux.</li> <li><b>RFF-205:</b> Hot oil reflow flux.</li> <li><b>HOR-210:</b> Reflow oil.</li> <li><b>FC-220:</b> Post HASL operations cleaner for achieving low ionic contamination and high SIR values for finished boards.</li> </ul>
<b>Micro-Etch</b> <ul style="list-style-type: none"> <li><b>ME-500:</b> concentrated microetch additive designed to improve the performance and stability of generic hydrogen peroxide/sulfuric acid microetches</li> <li><b>ME-510:</b> Stabilized and enhanced peroxide / sulfuric.</li> <li><b>ME-550:</b> Stabilized persulfate micro-etch.</li> <li><b>ME-560:</b> Potassium monopersulfate based micro-etch.</li> <li><b>ME-570:</b> Stabilized, liquid sodium persulfate micro-etch.</li> <li><b>ME-571:</b></li> </ul>
<b>Oxide Alternative</b> <ul style="list-style-type: none"> <li><b>Resin Bond 320:</b> Immersion or spray alternative oxide.</li> </ul>

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<b>Pumice</b> <ul style="list-style-type: none"> <li><b>AP-580:</b> Acid activated 3F pumice with anti-tarnish.</li> <li><b>AP-581:</b> Acid activated 3F pumice with anti-tarnish for hand pumicing</li> </ul>
<b>Screening Products</b> <ul style="list-style-type: none"> <li><b>SMS-400:</b> Cured soldermask stripper.</li> <li><b>SC-410:</b> Terpene based uncured LPI and legend ink screen cleaner.</li> <li><b>SC-411:</b> Biodegradable screen cleaner for uncured soldermask and legend inks from screens and parts.</li> <li><b>SC-416:</b> Biodegradable screen cleaner for uncured soldermask and legend inks from screens and parts.</li> <li><b>ER-425:</b> Screen cleaner emulsion remover.</li> </ul>
<b>Solder / Tin Strippers</b> <ul style="list-style-type: none"> <li><b>TSN-3000:</b> High speed, high loading, nitric stripper.</li> <li><b>TSN-3000R:</b> TSN-3000 Nitric strip replenisher</li> <li><b>TSOx-3001:</b> Biflouride/peroxide based stripper.</li> <li><b>TS-3002A/3003B:</b> Two step immersion stripper. Stabilized nitric acid first step, ferric chloride based finishing step.</li> <li><b>TSN-3100:</b> High speed, high loading, nitric stripper.</li> </ul>
<b>Waste Treatment</b> <ul style="list-style-type: none"> <li><b>MP-9210:</b> Sodium dimethyl dithiocarbamate for metal removal from chelated and non-chelated waste streams.</li> <li><b>MP-9220:</b> Metal precipitant.</li> <li><b>RT-9225:</b> Detackifier for photoresist precipitation of spent aqueous and semi-aqueous stripper solutions.</li> <li><b>MP-9230:</b> Calcium polysulfide based waste treatment additive for precipitating metal ions.</li> <li><b>CP-9260:</b> Cationic polymer designed for use in the flocculation of industrial wastewaters.</li> </ul>
<b>Process Equipment</b> <ul style="list-style-type: none"> <li><b>AUTOdose PC-1001:</b> Panel count controller.</li> <li><b>µETCH EC-2000:</b> Microetch control system.</li> <li><b>ETCHpro CC-4000:</b> Cupric Chloride etch controller.</li> <li><b>AUTOstrip PC-5040:</b> Resist stripper panel count control system.</li> <li><b>FILTERpro RS-5050:</b> Photoresist removal drum filter.</li> <li><b>Gravitrol SG-7000:</b> Tin strip specific gravity controller</li> </ul>

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